

IN THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Previously presented) An apparatus for processing a substrate, comprising:
 - a first manifold module configured to define and contain a fluid meniscus between a manifold module surface and a substrate surface;
 - a second manifold module being configured to connect with the first manifold module and to move the first manifold module into proximity to the substrate surface to generate the fluid meniscus; and
 - a manifold carrier for positioning the first manifold module to a region of the substrate to be processed;
wherein a processing surface of the first manifold module is defined beyond a plane of a bottom surface of the manifold carrier, and a processing surface of the first manifold module comprises a first conduit for applying a first fluid to the substrate surface, a second conduit for applying a second fluid to the substrate surface, and a third conduit for removing the first fluid and the second fluid from the substrate surface, the proximity of the first manifold defined to contain the fluid meniscus between the manifold module surface and the substrate surface.
2. (Cancel)
3. (Original) An apparatus for processing a substrate as recited in claim 1, wherein the connection is configured to supply fluids to the first manifold module and to remove fluids from the first manifold module.
4. (Original) An apparatus for processing a substrate as recited in claim 3, wherein the second manifold module is configured to supply a first fluid and a second fluid to

the first manifold module and to remove the first fluid and the second fluid from the first manifold module.

5. (Original) An apparatus for processing a substrate as recited in claim 4, wherein the first manifold module is configured to apply a first fluid and a second fluid to the substrate surface and to remove the first fluid and the second fluid from the substrate surface.

6. (Original) An apparatus for processing a substrate as recited in claim 1, wherein the second manifold module is configured to move vertically to connect with the first manifold module.

7. (Original) An apparatus for processing a substrate as recited in claim 1, wherein the fluid meniscus conducts one of a plating, etching, drying, and cleaning operation.

8.-9. (Cancel)

10.-16. (Cancel)

17. (Previously presented) An apparatus for processing a substrate, comprising:
a first manifold module having a processing face with a first conduit configured to apply a first fluid to a substrate surface, a second conduit for applying a second fluid to the substrate surface, and a third conduit for removing the first fluid and the second fluid from the substrate surface, the applying and the removing defining a fluid meniscus contained between the processing face and the substrate surface; and

a second manifold module being configured to move the processing face of the first manifold module proximate to the substrate surface and to deliver the first fluid and the second fluid to the first manifold module and to remove the first fluid and the second fluid that has been applied to the substrate from the first manifold module;

a manifold carrier for positioning the first manifold module to a region of the substrate to be processed, where a processing surface of the first manifold module is positioned beyond a plane of a bottom surface of the manifold carrier.

18. (Original) An apparatus for processing a substrate as recited in claim 17, wherein the second manifold has ports for delivering the first fluid and the second fluid to the first manifold, and the second manifold has at least one port for removing the first fluid and the second fluid that has been applied to the substrate from the first manifold.

19. (Original) An apparatus for processing a substrate as recited in claim 17, wherein the first manifold has ports for receiving the first fluid and the second fluid from the second manifold, and the first manifold has at least one port for delivering the first fluid and the second fluid that has been applied to the substrate to the second manifold module.

20. (Original) An apparatus for processing a substrate as recited in claim 17, wherein the first fluid is one of an etching fluid, a cleaning fluid, a drying fluid, and a plating fluid, and the second fluid is configured to reduce surface tension of the first fluid.

21. (Canceled)